2-2456589-2 ACTIVE

GRACE INERTIA | GRACE INERTIA 1.25

TE Internal #: 2-2456589-2

PCB Mount Header, Vertical, Wire-to-Board, 22 Position, 1.25 mm [. 05 in] Centerline, Fully Shrouded, Tin (Sn), Surface Mount, GRACE

INERTIA 1.25

View on TE.com >



Connectors > PCB Connectors > PCB Headers & Receptacles











PCB Connector Type: PCB Mount Header

PCB Mount Orientation: Vertical
Connector System: Wire-to-Board

Number of Positions: 22

Number of Rows: 2

Features

Product Type Features

Applied Pressure	Standard
PCB Connector Type	PCB Mount Header
Connector System	Wire-to-Board
Header Type	Fully Shrouded
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Connector Product Type	Connector Assembly
Configuration Features	
Number of Loaded Positions	22
Number of Signal Positions	22
Number of Power Positions	0
Connector Contact Load Condition	Fully Loaded
PCB Mount Orientation	Vertical
Number of Positions	22



Electrical Characteristics Operating Voltage Insulation Resistance Dielectric Withstanding Voltage (Max) Body Features Connector Profile Contact Profile Contact Underplating Material Contact Features Contact Mating Area Plating Material Finish Mating Tab Witch After Contact Mating Area Plating Material Hickness 1 um[40 µin] Mating Tab Witch Contact Shape & Form SMT Lead Contact Layout Inline Contact Rase Material Contact Rase Material Contact Rase Material Contact Rase Material Tin Contact Mating Area Plating Material Finish Matte Contact Mating Area Plating Material Tin (Sn) Contact Mating Area Plating Material Tin (Sn) Contact Type Blade Contact Current Rating (Max) 1.5 A Termination Features Termination Features Termination Method to PCB Mechanical Attachment Mating Retention With PCB Mount Alignment Type Pegs PCB Mount Alignment Type	Number of Rows	2
Departing Voltage Insulation Resistance Dielectric Withstanding Voltage (Max) Soo V Soody Features Connector Profile Contact Profile Primary Product Color Contact Features Contact Insulation Area Plating Material Finish Matte Contact Habrication Contact Habrication Contact Mating Area Plating Material Finish Mating Tab Width Contact Shape & Form SMT Lead Contact Layout Infine Contact Mating Area Plating Material Tin Contact Mating Area Plating Material Tin Contact Habrication Contact Shape & Form SMT Lead Contact Layout Infine Contact Mating Tab Thickness 3 mm PCB Contact Termination Area Plating Material Tin Contact Mating Area Plating Material Tin Contact Mating Area Plating Material Tin Contact Mating Area Plating Material Tin (Sn) Contact Type Blade Contact Type Blade Contact Current Rating (Max) Termination Features Termination Features Termination Methos to PCB Mating Retention Mating Retention With PCB Mount Alignment Type Pegs PCB Mount Alignment Type Pegs PCB Mount Alignment With PCB Mount Alignment With		2
Insulation Resistance Dielectric Withstanding Voltage (Max) Body Features Connector Profile Primary Product Color Natural Contact Underplating Material PCB Contact Termination Area Plating Material Finish Matte Contact Mating Area Plating Material Hickness 1 µm(40 µin) Mating Tab Width A5 mm Contact Shape & Form SMT Lead Contact Layout Inline Contact Base Material Contact Mating Area Plating Material Finish Mating Tab Width Contact Material Contact Material Contact Shape & Form SMT Lead Contact Material Material Contact Mating Area Plating Material Tin Contact Mating Area Plating Material Tin Sh Contact Mating Area Plating Material Tin Sh Contact Type Blade Contact Current Rating (Max) 1.5 A Termination Features Termination Method to PCB Surface Mount Mating Retention With PCB Mount Retention Type Pegs PCB Mount Alignment Type Pegs PCB Mount Alignment With PCB Mount Alignment With	Electrical Characteristics	
Belectric Withstanding Voltage (Max) Body Features Connector Profile Contact Profile Contact Features Contact Underplating Material PCB Contact Termination Area Plating Material Finish Matte Contact Fabrication Contact Fabrication Stamped & Formed Contact Fabrication Stamped & Formed Contact Fabrication Contact Fabrication Stamped & Formed Contact Fabrication SMI Lead Contact Shape & Form SMI Lead Contact Shape & Form SMI Lead Contact Base Material Contact Base Material Contact Base Material Contact Termination Area Plating Material Tin Contact Mating Area Plating Material Tin Contact Mating Area Plating Material Tin (Sn) Contact Mating Area Plating Material Tin (Sn) Contact Uppe Blade Contact Surper Contact Gurrent Rating (Max) Termination Features Lermination Method to PCB Surface Mount Mating Retention PCB Mount Retention Type Pegs PCB Mount Alignment With PCB Mount Alignment With PCB Mount Alignment With	Operating Voltage	50 VAC
Connector Profile Low Primary Product Color Contact Features Contact Underplating Material Nickel PCB Contact Termination Area Plating Material Finish Matte Contact I abrication Stamped & Formed Contact Mating Area Plating Material Thickness 1 µm(40 µin) Mating Lab Width 45 mm Contact Shape & Form SMT Lead Contact Layout Inline Contact Base Material Contact Hamilian Area Plating Material Thickness 3 mm Contact Base Material Contact Layout Inline Contact Mating Area Plating Material Thickness 3 mm PCB Contact Layout Inline Contact Base Material Copper Alloy Mating Tab Thickness 3 mm PCB Contact Termination Area Plating Material Tin Contact Mating Area Plating Material Tin Contact Mating Area Plating Material Tin (So) Contact Type Blade Contact Type Blade Contact Current Rating (Max) 1.5 A Termination Features Termination Method to PCB Surface Mount Mating Retention With PCB Mount Retention Type Pegs PCB Mount Alignment Type Pegs PCB Mount Alignment Type Pegs PCB Mount Alignment Method With	Insulation Resistance	500 ΜΩ
Connector Profile Primary Product Color Contact Features Contact Underplating Material PCB Contact Termination Area Plating Material Finish Matte Contact I abrication Contact Mating Area Plating Material Thickness I µm[40 µin] Mating Lab Width A5 mm Contact Base Material Contact Base Material Contact Layout Inline Contact Base Material Contact Termination Area Plating Material Mating Lab Thickness Jamm Contact Mating Area Plating Material Tin (Sn) Contact Type Blade Contact Type Blade Contact Current Rating (Max) Termination Features Termination Method to PCB Surface Mount Mating Retention With PCB Mount Retention Type Pegs PCB Mount Alignment Type PCB Mount Retention With	Dielectric Withstanding Voltage (Max)	500 V
Primary Product Color Contact Features Contact Underplating Material PCB Contact Termination Area Plating Material Finish Contact Fabrication Contact Mating Area Plating Material Thickness Mating Iab Width Contact Shape & Form Contact Layout Contact Base Material Contact Base Material Contact Base Material Contact Base Material Contact Haring Area Plating Material Tin Contact Mating Area Plating Material Tin (Sn) Contact Type Blade Contact Type Blade Contact Current Rating (Max) Termination Method to PCB Surface Mount Methanical Attachment Mating Retention PCB Mount Retention Type Pegs PCB Mount Alignment Type With PCB Mount Alignment With	Body Features	
Contact Underplating Material PCB Contact Termination Area Plating Material Finish Contact Fabrication Contact Fabrication Contact Mating Area Plating Material Thickness 1 µm(40 µin) Mating Tab Width A5 mm Contact Shape & Form SMT Lead Contact Layout Inline Contact Base Material Contact Base Material Contact Termination Area Plating Material Tin Contact Termination Area Plating Material Tin Contact Mating Area Plating Material Tin (Sn) Contact Type Blade Contact Type Blade Contact Current Rating (Max) Termination Method to PCB Mechanical Attachment Mating Retention PCB Mount Retention Type PCB Mount Alignment Type PCB Mount Alignment With PCB Mount Alignment With	Connector Profile	Low
Contact Underplating Material PCB Contact Termination Area Plating Material Finish Contact Fabrication Stamped & Formed Contact Mating Area Plating Material Thickness 1 µm[40 µin] Mating Tab Width 45 mm Contact Shape & Form SMT Lead Contact Layout Inline Contact Base Material Contact Base Material Contact Base Material Contact Termination Area Plating Material Tin Contact Termination Area Plating Material Tin Contact Mating Area Plating Material Tin (Sn) Contact Type Blade Contact Type Blade Contact Current Rating (Max) Termination Method to PCB Mechanical Attachment Mating Retention PCB Mount Retention Type Pegs PCB Mount Alignment Type Pegs PCB Mount Alignment With PCB Mount Alignment With	Primary Product Color	Natural
PCB Contact Termination Area Plating Material Finish Stamped & Formed Contact Mating Area Plating Material Thickness 1 \mu	Contact Features	
Contact Fabrication Stamped & Formed Contact Mating Area Plating Material Thickness 1 \(\mu\) \(\m\	Contact Underplating Material	Nickel
Contact Mating Area Plating Material Thickness 1 μm[40 μin] Mating Tab Width 45 mm Contact Shape & Form 5MT Lead Contact Layout Inline Contact Base Material Copper Alloy Mating Tab Thickness 3mm PCB Contact Termination Area Plating Material Tin Contact Mating Area Plating Material Tinish Matte Contact Mating Area Plating Material Tinish Matte Contact Mating Area Plating Material Tinish Matte Contact Type Blade Contact Current Rating (Max) 1.5 A Termination Features Termination Method to PCB Surface Mount Mechanical Attachment Mating Retention With PCB Mount Retention Type Pegs PCB Mount Alignment Type Pegs PCB Mount Retention With	PCB Contact Termination Area Plating Material Finish	Matte
Mating Tab Width Contact Shape & Form SMT Lead Contact Layout Inline Contact Base Material Contact Base Material Contact Base Material Contact Termination Area Plating Material Contact Mating Area Plating Material Contact Type Blade Contact Current Rating (Max) Termination Features Termination Method to PCB Mating Retention PCB Mount Retention Type PCB Mount Alignment Type PCB Mount Alignment PCB Mount Retention With PCB Mount Retention With PCB Mount Retention With	Contact Fabrication	Stamped & Formed
Contact Shape & Form SMT Lead Contact Layout Inline Contact Base Material Copper Alloy Mating Tab Thickness3 mm PCB Contact Termination Area Plating Material Tin Contact Mating Area Plating Material Finish Matte Contact Mating Area Plating Material Tinish Tin (Sn) Contact Type Blade Contact Type Blade Contact Current Rating (Max) 1.5 A Termination Features Termination Method to PCB Surface Mount Mating Retention With PCB Mount Retention Type Pegs PCB Mount Alignment Type Pegs PCB Mount Retention With PCB Mount Retention With PCB Mount Retention With	Contact Mating Area Plating Material Thickness	1 μm[40 μin]
Contact Layout Inline Contact Base Material Copper Alloy Mating Tab Thickness .3 mm PCB Contact Termination Area Plating Material Tin Contact Mating Area Plating Material Tin (Sn) Contact Mating Area Plating Material Tinish Matte Contact Type Blade Contact Current Rating (Max) 1.5 A Termination Features Termination Method to PCB Surface Mount Mechanical Attachment Mating Retention With PCB Mount Retention Type Pegs PCB Mount Alignment Type Pegs PCB Mount Retention With PCB Mount Retention With	Mating Tab Width	.45 mm
Contact Base Material Copper Alloy Mating Tab Thickness 3 mm PCB Contact Termination Area Plating Material Tin Contact Mating Area Plating Material Finish Matte Contact Mating Area Plating Material Finish Tin (Sn) Contact Type Blade Contact Current Rating (Max) 1.5 A Termination Features Termination Method to PCB Surface Mount Mating Retention With PCB Mount Retention Type Pegs PCB Mount Alignment Type Pegs PCB Mount Retention With	Contact Shape & Form	SMT Lead
Mating Tab Thickness .3 mm PCB Contact Termination Area Plating Material Tin Contact Mating Area Plating Material Finish Matte Contact Mating Area Plating Material Tin (Sn) Contact Type Blade Contact Current Rating (Max) 1.5 A Termination Features Termination Method to PCB Surface Mount Mating Retention With PCB Mount Retention Type Pegs PCB Mount Alignment Type Pegs PCB Mount Retention With PCB Mount Retention With PCB Mount Retention With PCB Mount Retention With	Contact Layout	Inline
PCB Contact Termination Area Plating Material Contact Mating Area Plating Material Finish Contact Mating Area Plating Material Contact Mating Area Plating Material Contact Type Blade Contact Current Rating (Max) 1.5 A Termination Features Termination Method to PCB Surface Mount Mating Retention PCB Mount Retention Type Pegs PCB Mount Alignment Type PCB Mount Retention PCB Mount Retention With	Contact Base Material	Copper Alloy
Contact Mating Area Plating Material Finish Matte Contact Mating Area Plating Material Tinish Tin (Sn) Contact Type Blade Contact Current Rating (Max) 1.5 A Termination Features Termination Method to PCB Surface Mount Mechanical Attachment Mating Retention With PCB Mount Retention Type Pegs PCB Mount Alignment Type Pegs PCB Mount Retention With PCB Mount Alignment Method With PCB Mount Alignment With PCB Mount Alignment With	Mating Tab Thickness	.3 mm
Contact Mating Area Plating Material Contact Type Blade Contact Current Rating (Max) 1.5 A Termination Features Termination Method to PCB Surface Mount Mechanical Attachment Mating Retention PCB Mount Retention Type PCB Mount Alignment Type PCB Mount Retention With PCB Mount Retention With PCB Mount Retention With PCB Mount Alignment Type Pegs PCB Mount Alignment With	PCB Contact Termination Area Plating Material	Tin
Contact Type Blade Contact Current Rating (Max) 1.5 A Termination Features Termination Method to PCB Surface Mount Mechanical Attachment Mating Retention With PCB Mount Retention Type Pegs PCB Mount Alignment Type Pegs PCB Mount Retention With PCB Mount Retention With PCB Mount Retention With	Contact Mating Area Plating Material Finish	Matte
Contact Current Rating (Max) Termination Features Termination Method to PCB Surface Mount Mechanical Attachment Mating Retention PCB Mount Retention Type Pegs PCB Mount Alignment Type PCB Mount Retention With PCB Mount Retention With With With With With With	Contact Mating Area Plating Material	Tin (Sn)
Termination Features Termination Method to PCB Surface Mount Mechanical Attachment Mating Retention PCB Mount Retention Type Pegs PCB Mount Alignment Type PCB Mount Retention With PCB Mount Retention With With	Contact Type	Blade
Termination Method to PCB Mechanical Attachment Mating Retention PCB Mount Retention Type PCB Mount Alignment Type PCB Mount Retention With PCB Mount Retention With PCB Mount Alignment Type With PCB Mount Alignment With	Contact Current Rating (Max)	1.5 A
Mechanical Attachment Mating Retention PCB Mount Retention Type PCB Mount Alignment Type PCB Mount Retention With PCB Mount Alignment With With	Termination Features	
Mating Retention PCB Mount Retention Type PCB Mount Alignment Type PCB Mount Retention With PCB Mount Alignment With	Termination Method to PCB	Surface Mount
PCB Mount Retention Type PCB Mount Alignment Type PCB Mount Retention With PCB Mount Alignment With	Mechanical Attachment	
PCB Mount Alignment Type PCB Mount Retention PCB Mount Alignment With With	Mating Retention	With
PCB Mount Retention With PCB Mount Alignment With	PCB Mount Retention Type	Pegs
PCB Mount Alignment With	PCB Mount Alignment Type	Pegs
	PCB Mount Retention	With
Housing Features	PCB Mount Alignment	With
	Housing Features	



Mating Entry Location	Тор
Housing Material	Nylon
Centerline (Pitch)	1.25 mm[.05 in]
Usage Conditions	
Housing Temperature Rating	Standard
Operating Temperature Range	-40 - 105 °C[-40 - 221 °F]
Operation/Application	
Assembly Process Feature	Carrier Tape
Shielded	No
Circuit Application	Signal
Industry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	

Tape & Reel

Product Compliance

Packaging Method

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2025 (247) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Not reviewed for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits

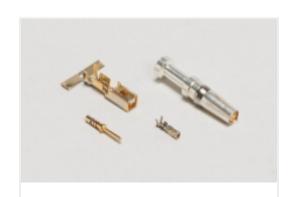


as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulations, TE's information on SVHC in articles for this part number is still based on the European Chemical Agency (ECHA) 'Guidance on requirements for substances in articles' (Version: 2, April 2011), applying the 0.1% weight on weight concentration threshold at the finished product level. TE is aware of the European Court of Justice ruling of September 10th, 2015 also known as O5A (Once An Article Always An Article) stating that, in case of 'complex object', the threshold for a SVHC must be applied to both the product as a whole and simultaneously to each of the articles forming part of its composition. TE has evaluated this ruling based on the new ECHA "Guidance on requirements for substances in articles" (June 2017, version 4.0) and will be updating its statements accordingly.

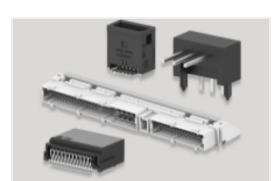
Compatible Parts



Also in the Series | GRACE INERTIA 1.25



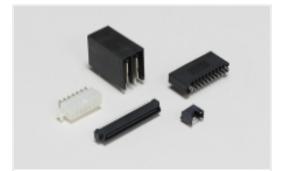
Connector Contacts(2)



PCB Headers & Receptacles(76)



Rectangular Connector Housings(2)



Standard Rectangular Connectors(2)



Wire-to-Board Connector Assemblies & Housings(42)



Wire-to-Board Headers & Receptacles (76)

Customers Also Bought





TE Part #1-171825-0 EIS HSG



TE Part #171826-5
POST HDR ASSY HDR AMP EI CONN



TE Part #292207-5 MINI CT SGL DIP V 5P NAT



TE Part #292207-6 MINI CT SGL DIP V 6P NAT



TE Part #1-316133-2 DYNAMIC D-3200 HDR ASSY 6P V



TE Part #5-1744105-4
EP HDR ASSY 5P omit 2&4,black



TE Part #1971032-5
5P HEADER ASSEMBLY FOR GIC 2.0
EV



TE Part #2360540-6 SGI 1.25 HDR, 6P, VT, Key A, Natural



TE Part #2360540-8 SGI 1.25 HDR, 8P, VT, Key A, Natural



TE Part #2367943-5
GI2.0EV VT SMT Poting HDR,NTL,Key A,5P

Documents

Product Drawings

Header Assy, 22pos, VT, KeyA, SGI 1.25

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2-2456589-2_A.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_2-2456589-2_A.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2-2456589-2_A.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use

Product Specifications

PCB Mount Header, Vertical, Wire-to-Board, 22 Position, 1.25 mm [.05 in] Centerline, Fully Shrouded, Tin (Sn), Surface Mount, GRACE INERTIA 1.25



Application Specification

English

Agency Approvals

UL Report

English